

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph 99 of the specification as follows:

[0099] Fig. 8 illustrates the main part of a micro-asperity pattern forming apparatus 1G according to a seventh embodiment for forming an asperity pattern on a resin thin film. The seventh embodiment of Fig. 8 is different from the third embodiment of Fig. 4 in that the pressurizing mechanism 2A which holds the embossment roll 3A rotatably ~~by pressurizing mechanisms 2a and 2b~~ is configured so as to be movable in the vertical direction while applying pressure to the resin thin film 4, and that a moving mechanism 8A is placed on an embossment-roll-rotation-axis-direction moving mechanism 8B so as to be movable in the embossment roll rotation axis direction.